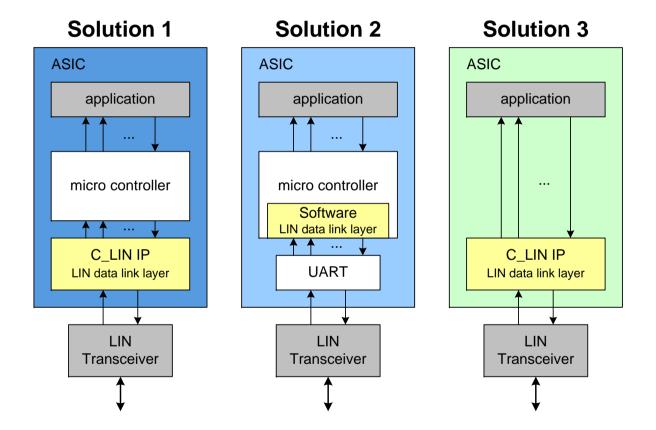
# **C\_LIN** intellectual property

# Solutions



#### **Automotive Electronics**



### **C\_LIN** intellectual property

# Solutions

Solution 1



- → most expensive solution (µC + C\_LIN)
- but thinkable if micro controller not able to support all jobs incl. LIN data link layer
- bridge between C\_LIN IP and μC needed (message handler with μC interface; not part of C\_LIN IP; responsibility of customer)

Solution 2



- target solution of LIN idea (master/slave)
- LIN data link layer done by software

Solution 3



- most compact and cost efficient solution
- solution without micro controller (slave only)
- → C\_LIN IP directly connected to application



## **C\_LIN** intellectual property

# Solution 3 – Example: air condition circuit

- → Inputs (temperature sensor and flap status) directly connected to transmit message buffers
- Outputs of the receive message buffers directly connected to power amplifiers for actuators
- → No message handler

